Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	101	257/706,717,718,720,796,675.ccls. and @pd>"20050622"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/27 13:53
L2	3	package and (die same wet$4 same (adhesion barrier glue adhesion/barrier)) and heat and solder and @pd>"20050622"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 13:57
L3	12	package and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder and @pd>"20050622"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/27 13:57
L4	15	packag$3 and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder and @pd>"20050622"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:02
L5	10	packag$3 and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder and heat and @pd>"20050622"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:11
L6	100	packag$3 and ((die chip) same solder) same (heat adj (sink spreader)) and @pd>"20050622"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/27 14:08
L7	120	packag$3 and ((die chip) same solder) same (heat adj (sink spreader)) and @pd>"20050622"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:09
L8	0	(packag$3 and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder and heat).clm.	US-PGPUB	OR	ON	2005/09/27 14:11
L9	3	(packag$3 and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder).clm.	US-PGPUB	OR	ON	2005/09/27 14:12
L10	4	(packag$3 and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier))).clm.	US-PGPUB	OR	ON	2005/09/27 14:12

S1	6	(("6471115") or ("6495397")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/27 13:52
S2	2	("6559536").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 12:18
S3	779	257/675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 12:44
S4	1248	257/706.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 13:15
S5	974	257/717.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 13:16
S6	2638	257/717,718,720.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 13:16
S7	2074	257/717,718.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 13:16
S8	974	257/717.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 13:32
S9	691	257/796.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 13:32
S10	71	package and (die same wet$4 same (adhesion barrier glue adhesion/barrier)) and heat and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/27 13:56

S11	292	package and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/27 13:57
S12	341	packag$3 and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/27 14:01
S13	206	packag$3 and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder and heat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/27 14:04
S14	288	packag$3 and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder and (heat thermal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 10:47
S15	81	packag$3 and ((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder and (heat adj (sink spreader))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 12:46
S16	7	((die chip) same wet$4 same (adhesion barrier glue adhesion/barrier)) and solder and (heat adj (sink spreader)) not packag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 12:36
S17	65	packag$3 and ((die chip) same (Ti TiN Ta TaN) same (Ni NiV) same (Au Pt Pd)) and solder and (heat adj (sink spreader))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 13:01
S18	2060	packag$3 and ((die chip) same solder) same (heat adj (sink spreader))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/27 14:05
S19	2	("5777385").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 14:42
S20	2	("6162659").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 14:42

S21	142	"257"/$.ccls. and package and (solder with AuSn)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 17:51
S22	22	"257"/$.ccls. and package and ((solder with AuSn) same (heat adj (sink spreader slug)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/24 12:29
S23	1	"257"/$.ccls. and package and ((solder with Au/Sn) same (heat adj (sink spreader slug)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 17:58
S24	4	"257"/$.ccls. and package and ((solder with AuSn with eutectic) same (heat adj (sink spreader slug)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/24 12:34
S25	50	(reset$3 near3 data) with memory with reference	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/24 18:57